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- A Member of the MuxIt[™] Serializer-Deserializer Building-Block Chip Family
- Supports Deserialization of One Serial Link Data Channel Input at Rates up to 200 Mbps
- PLL Lock/Valid Input Provided to Enable Parallel Data and Clock Outputs
- Cascadable With Additional SN65LVDS152
 MuxIt Receiver–Deserializers for Wider
 Parallel Output Data Channel Widths
- LVDS Compatible Differential Inputs and Outputs Meet or Exceed the Requirements of ANSI TIA/EIA-644-A
- LVDS Input and Output ESD Protection Exceeds 12 kV HBM
- LVTTL Compatible Inputs for Lock/Valid and Enables Are 5-V Tolerant
- Operates With 3.3-V Supply
- Packaged in 32-Pin DA Thin Shrink Small-Outline Package With 26-Mil Terminal Pitch

(Marked as 65LVDS152) (TOP VIEW) DI+ Ŋ∨cc DI- I 2 31 LVI GND [П мсі– 3 30 LCI+ MCI+ LCI− [∏ GND 5 28 GND [Посо 6 27 CO EN [7 **∏** DO−9 26 V_{CC} [25 **∏** DO–8 8 GND [9 ∏ DO-7 24 II DO-6 V_{CC} L 10 23 11 DO-5 22 V_{CC} GND 12 ∏ DO-4 21 GND II 13 20 II DO-3 EN | 14 19 || DO-2 CO- 15 18 Π DO-1 CO+ [] 16 17 **∐** DO−0

SN65LVDS152DA

description

MuxIt is a family of general-purpose, multiple-chip building blocks for implementing parallel data serializers and deserializers. The system allows for wide parallel data to be transmitted through a reduced number of transmission lines over distances greater than can be achieved with a single-ended (e.g., LVTTL or LVCMOS) data interface. The number of bits multiplexed per transmission line is user selectable, allowing for higher transmission efficiencies than with other existing fixed ratio solutions. MuxIt utilizes the LVDS (TIA/EIA-644-A) low voltage differential signaling technology for communications between the data source and data destination.

The MuxIt family initially includes three devices supporting simplex communications: the SN65LVDS150 phase locked loop frequency multiplier, the SN65LVDS151 serializer-transmitter, and the SN65LVDS152 receiver-deserializer.

The SN65LVDS152 consists of three LVDS differential transmission line receivers, an LVDS differential transmission line driver, a 10-bit serial-in/parallel-out shift register, plus associated input and output buffers. It receives serialized data over an LVDS transmission line link, deserializes (demultiplexes) it, and delivers it on parallel data outputs, DO-0 through DO-9. Data received over the link is clocked at a factor of M times the original parallel data frequency. The multiplexing ratio M, or number of bits per data clock cycle, is programmed with configuration pins (M1 \rightarrow M5) on the companion SN65LVDS150 MuxIt programmable PLL frequency multiplier. Up to 10 bits of data may be deserialized and output by each SN65LVDS152. Two or more SN65LVDS152 units may be connected in series (cascaded) to accommodate wider parallel data paths for higher serialization values. The range of multiplexing ratio M supported by the SN65LVDS150 MuxIt programmable PLL frequency multiplier is between 4 and 40. Table 1 shows some of the combinations of LCI and MCI supported by the SN65LVDS150 MuxIt programmable PLL frequency multiplier.



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description (continued)

Data is serially shifted into the SN65LVDS152 shift register on the falling edges of the M-clock input (MCI). The data is latched out in parallel from the SN65LVDS152 shift register on the second rising edge after the first falling edge of the M-clock following a rising edge of the link clock input (LCI). The SN65LVDS152 includes LVDS differential line receivers for both the serialized link data stream (DI) and link clock (LCI). High-speed signals from the SN65LVDS150 MuxIt programmable frequency multiplier (MCI), plus the input and output for cascaded data (DI, CO) are carried over differential connections to minimize skew and jitter. Examples of operating waveforms for values of M=4 and M=10 are provided in Figure 1.

The enable input (EN) along with internal power-on reset (POR) controls the outputs. When Vcc is below 1.5 volts, or when EN is low, outputs are disabled. When V_{CC} is above 3 V and EN is high, outputs are enabled and operating to specifications.

Parallel data bits are output from DO—n outputs in an order dependent on the value of the multiplexing ratio (frequency multiplier value) M. For values of M from 4 through 10, the cascade output (CO+/–) is not used, and only the top M parallel outputs (DO—9 through DO—[10—M]) are used. The data bit output on DO—9 corresponds to the data bit input on DI—[M—1] of the SN65LVDS151 serializer. Likewise, the data bit output on DO—[10—M] will correspond to the data bit input on DI—0 of the SN65LVDS151 serializer.

For values of M greater than 10, the cascade output (CO+/-) is used to connect multiple SN65LVDS152 deserializers. In this case the higher-order unit(s) output 10 bits each of the highest numbered bits that are input into the SN65LVDS151 serializer(s). The lowest numbered input bits are output on the lowest-order SN65LVDS152 deserializer in descending order from output DO-9. The number of bits is equal to M mod(10). Table 2 reflects this information, where X = M mod(10)

Table 1. Example Combinations of LCI and MCI Supported by the SN65LVDS150 MuxIt Programmable PLL Frequency Multiplier

	LCI,	MHz	MCI, MHz		
M	MINIMUM	MINIMUM MAXIMUM		MAXIMUM	
4	5	50	20	200	
10	5	20	50	200	
20	5	10	100	200	
40	5	5	200	200	

Table 2. Output Data Blts as a Function of Multiplier Value M

	X = 1	X = 2	X = 3	X = 4	X = 5	X = 6	X = 7	X = 8	X = 9	X = 0
DO-9 output bit	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6	DI-7	DI-8	DI-9
DO-8 output bit	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6	DI-7	DI-8
DO-7 output bit	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6	DI-7
DO-6 output bit	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5	DI-6
DO-5 output bit	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4	DI-5
DO-4 output bit	Invalid	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3	DI-4
DO-3 output bit	Invalid	Invalid	Invalid	Invalid	Invalid	Invalid	DI-0	DI-1	DI-2	DI-3
DO-2 output bit	Invalid	DI-0	DI-1	DI-2						
DO-1 output bit	Invalid	DI-0	DI-1							
DO-0 output bit	Invalid	DI-0								

Additional information on output bit ordering in cascaded applications can be found in the MuxIt Application Report.



description (continued)

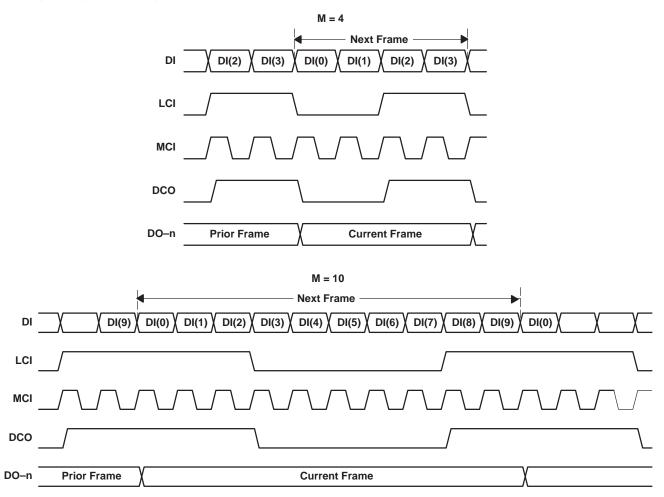
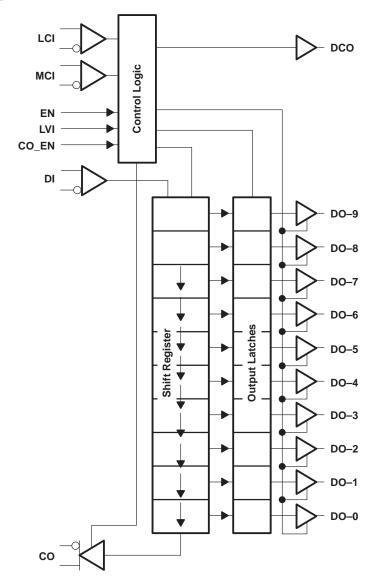


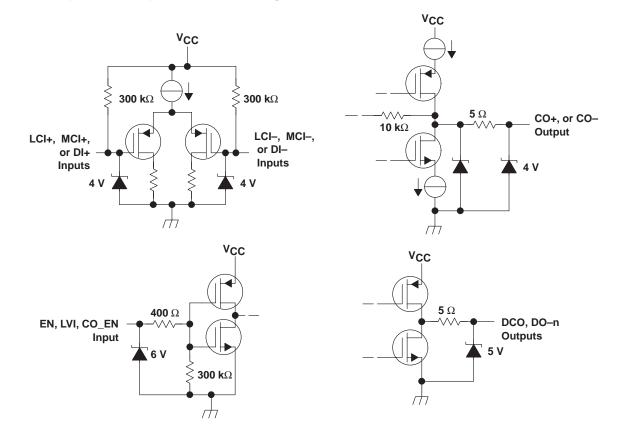
Figure 1. Operating Waveform Examples

functional block diagram





equivalent input and output schematic diagrams



Terminal Functions

TERMINAL					
NAME	NO.	1/0	LEVEL	DESCRIPTION	
CO-, CO+	15, 16	Output	LVDS	Cascade output. This is used to connect to additional SN65LVDS152 units when the multiplexing ratio M (and M-clock) value is greater than 10.	
CO_EN	7	Input	LVTTL	Cascade output enable. Used to control the CO output. A high-level input enables the CO output, a low-level input disables the CO output.	
DCO	27	Output	LVTTL	Data clock output. This is the recovered (original frequency) clock that is synchronized the deserialized parallel data.	
DI+, DI-	1, 2	Input	LVDS	Link data input. This is the data being received from the source end of the serialized Also used for cascade data input from additional SN65LVDS152 units when multiplexing ratio M value is greater than 10.	
EN	14	Input	LVTTL	Enable. Used to control overall device operation. A high-level input enables the devic low-level input disables the device by resetting the internal latches and forcing the CO LVTTL outputs to a high-impedance state.	
GND	3, 6, 9, 12, 13, 28	Power	NA	Circuit ground	
LCI+, LCI-	4, 5	Input	LVDS	Link clock input. This is the data block synchronization clock received from the source end of the serialized link.	
LVI	31	Input	LVTTL	Lock/valid input. This is a signal required for proper Muxlt system operation. It is to be directly connected to the LVO output of an SN65LVDS150. It is used to inhibit the operation of this device until after the PLL has stabilized. A low level input disables the data and clock outputs, a high level input enables the outputs	
MCI+, MCI-	29,30	Input	LVDS		
DO-0-DO-9	17–26	Output	LVTTL	Parallel data outputs. Data from the serial shift register is transferred to the output dat latches in synchronization with the rising edge of LCI.	
VCC	8, 10, 11, 32	Power	NA	Supply voltage	

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.5 V to 4 V
Input voltage range: EN, LVI, CO_EN	–0.5 V to 5.5 V
LCI±, MCI±, DI±, CO±	–0.5 V to 4 V
Electrostatic discharge, human body model (see Note 2): LCI±, MCI±, DI±, CO±, ar	nd GND ±12 kV
All pins	±2 kV
Charged-device model (see Note 3): All pins	±500 V
Continuous power dissipation See	Dissipation Rating Table
Storage temperature range	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
 - 2. Tested in accordance with JEDEC Standard 22, Test Method A114–B.
 - 3. Tested in accordance with JEDEC Standard 22, Test Method C101.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 85°C POWER RATING
DA	1453 mW	11.6 mW/°C	756 mW



recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		3	3.3	3.6	V
High-level input voltage, VIH		2		VCC	V
Low-level input voltage, V _{IL}	EN, LVI, CO_EN			0.8	V
Magnitude of differential input voltage, VID		0.1		0.6	V
Common-mode input voltage, V _{IC}	LCI±, MCI±, DI±	$\frac{ V_{\text{ID}} }{2}$		$2.4 - \frac{ V_{ID} }{2}$	٧
				V _{CC} – 0.8	V
Operating free-air temperature, TA	-40		85	°C	

timing requirements

	PARAMETERS	TEST CONDITIONS	MIN	MAX	UNIT
t _{su(1)} Clock setu	up time, MCI↓ before LCI↑	0 5	0		ns
t _{SU(2)} Clock setu	up time, LCI↑ before MCI↓	See Figure 2	1		ns
t _{su(3)} Link data	setup time, DI before MCI↓	Coo Figure 2	0.3		ns
t _{h(3)} Link data	hold time, DI after MCI↓	See Figure 3	0.5		ns

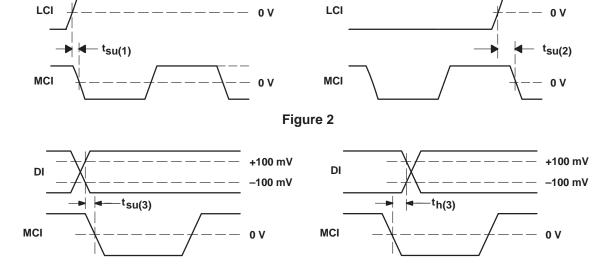


Figure 3. Input Data and M-Clock Setup and Hold Time Waveforms

SN65LVDS152 MuxIt™ RECEIVER-DESERIALIZER

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electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT		
V _{ITH+}	Positive-going differential inp	out voltage threshold	0 5: 1			100	.,	
VITH-	Negative-going differential in	put voltage threshold	See Figure 4	-100			mV	
V _{OD(SS)}	Steady-state differential outp	out voltage magnitude	B 400 0 W 400 W	247	340	454	mV	
Δ V _{OD(SS)}	Change in steady-state diffe magnitude between logic sta		R _L = 100 Ω , V _{ID} = ±100 mV, See Figures 5 and 6	-50		50	mV	
V _{OC} (SS)	Steady-stade common-mode	e output voltage		1.125		1.375	V	
ΔVOC(SS)	Change in steady-state com voltage between logic states		See Figure 7	-50		50	mV	
VOC(PP)	Peak-to-peak change comm	on-mode output voltage			50	150	mV	
Vон	High-level output voltage	DO - DOO	I _{OH} = -8 mA	2.4				
VOL	Low-level output voltage	DO-n, DCO	I _{OL} = 8 mA			0.4	V	
			Enabled, $R_L = 100 \Omega$,		14	25		
			Disabled		0.5	1		
Icc	Supply current		$ \begin{split} f_{\mbox{(MCI)}} &= 200 \mbox{ MHz}, \\ f_{\mbox{(LCI)}} &= 20 \mbox{ MHz}, \mbox{ R}_{\mbox{L}} = 100 \ \Omega, \\ DI - n &= 101010101010 \mbox{ at } 200 \mbox{ Mbit/s} \end{split} $		35	60	mA	
			V _I = 0 V	-2		-20		
j ¹ 1	Input current	LCI, MCI, DI inputs	V _I = 2.4 V	-1.2			μΑ	
I _{ID}	Differential input current	LCI, MCI, DI inputs	$V_{IC} = 0.05 \text{ V to } 2.35 \text{ V},$ $V_{ID} = \pm 0.1 \text{ V}$	-2		2	μΑ	
I _{I(OFF)}	Power-off input current	LCI, MCI, DI inputs	V _{CC} = 0 V , V _I = 3.6 V			20	μΑ	
lіН	High-level input current	EN, LVI, CO_EN	V _{IH} = 2 V			20	μΑ	
I _I L	Low-level input current	EN, LVI, CO_EN	V _{IL} = 0.8 V			10	μΑ	
	Chart singuit autout aumant	со	V_{O+} or $V_{O-} = 0 V$	-10		10	mA	
los	Short-circuit output current	100	V _{OD} = 0 V	-10		10	mA	
	High-impedance output	CO	V- 0 V or V	-5		5		
loz	current	DO-n, DCO	VO = 0 A or ACC	-5		5	μA	
l _{O(OFF)}	Power-off output current	CO	$V_{CC} = 1.5 \text{ V}$, $V_{O} = 3.6 \text{ V}$	-5		5	μΑ	
Cl	Input capacitance	LCI, MCI, DI inputs	$V_{ID} = (0.4\sin(4E6\pi t) + 0.5) V$		3		pF	

[†] All typical values are at $T_A = 25^{\circ}C$ and with $V_{CC} = 3.3 \text{ V}$.

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switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t d(1)	Propagation delay time, LCI↑ to DCO↑			2	3	
^t d(2)	Delay time, MCI↑ to DO–n			3.3	5.5	
t _{su(4)}	Set-up time, DO-n valid to DCO↑	See Figure 8	5			ns
th(4)	Hold time, DCO↑ to DO-n valid		5			
^t d(3)	Delay time, MCI↓ to CO	See Figure 9		2.9	4.5	ns
t _r	Differential output signal rise time, CO	$R_L = 100 \Omega$, $C_L = 10 pF$, See Figure 10	0.3	0.8	1.5	ns
·	Output signal rise time, DCO, DO-n	C _L = 10 pF, See Figure 11		0.6	1.5	
t _f	Differential output signal fall time, CO	$R_L = 100 \Omega$, $C_L = 10 pF$, See Figure 10	0.3	0.8	1.5	ns
Ī '	Output signal fall time, DCO, DO-n C _L = 10 pF, See Fig			0.6	1.5	<u> </u>
t _{sk(p)}	Pulse skew (t _{PHL} - t _{PLH}), CO	$R_L = 100 \Omega$, $C_L = 10 pF$, See Figure 10		0	300	ps
^t PZH	Propagation delay time, high-impedance to high-level output (DCO only)	EN to DCO, DO-n,		5	15	
^t PZL	Propagation delay time, high-impedance to low-level output	$C_{i} = 10 \text{ pF},$		5	15	ns
^t PHZ	Propagation delay time, high-level to high-impedance output	See Figure 12		5	15	
tPLZ	Propagation delay time, low-level to high-impedance output			6	15	
^t PZH	Propagation delay time, high-impedance to high-level output (DCO only)	LVI to DCO, DO-n		5	15	
tPZL	Propagation delay time, high-impedance to low-level output	$C_{I} = 10 \text{ pF},$		5	15	ns
^t PHZ	Propagation delay time, high-level to high-impedance output	See Figure 12		5	15	
tPLZ	Propagation delay time, low-level to high-impedance output			5	15	



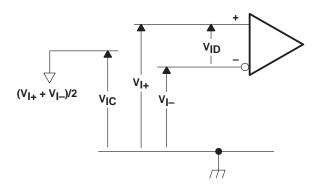


Figure 4. Receiver Voltage Definitions

Table 3. Receiver Minimum and Maximum Input Threshold Test Voltages

APP VOLT	LIED AGES	RESULTING DIFFERENTIAL INPUT VOLTAGE	RESULTING COMMON- MODE INPUT VOLTAGE
V _{I+}	٧١_	V _{ID}	V _{IC}
1.25 V	1.15 V	100 mV	1.2 V
1.15 V	1.25 V	−100 mV	1.2 V
2.4 V	2.3 V	100 mV	2.35 V
2.3 V	2.4 V	−100 mV	2.35 V
0.1 V	0 V	100 mV	0.05 V
0 V	0.1 V	−100 mV	0.05 V
1.5 V	0.9 V	600 mV	1.2 V
0.9 V	1.5 V	−600 mV	1.2 V
2.4 V	1.8 V	600 mV	2.1 V
1.8 V	2.4 V	−600 mV	2.1 V
0.6 V	0 V	600 mV	0.3 V
0 V	0.6 V	−600 mV	0.3 V

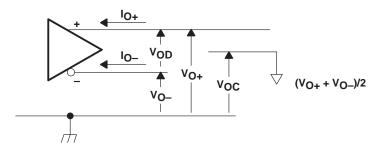


Figure 5. Driver Voltage and Current Definitions



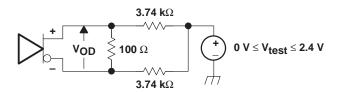
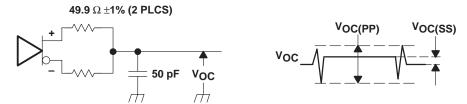


Figure 6. V_{OD} Test Circuit



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_{Γ} or $t_{\Gamma} \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, Pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T. The measurement of V_{OC(PP)} is made on test equipment with a -3 dB bandwidth of at least 5 GHz.

Figure 7. Test Circuit and Definitions for the Driver Common-Mode Output Voltage

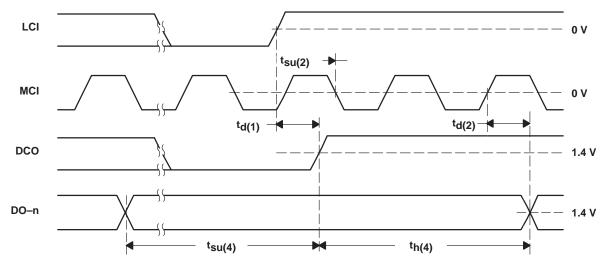


Figure 8. Data Clock and Data Output Timing Waveforms

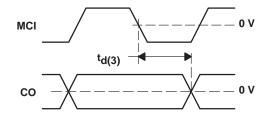
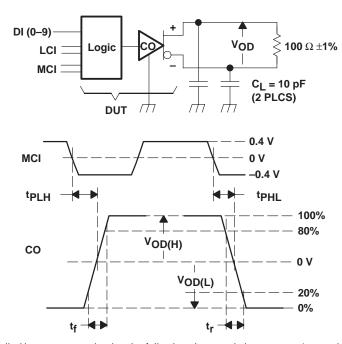
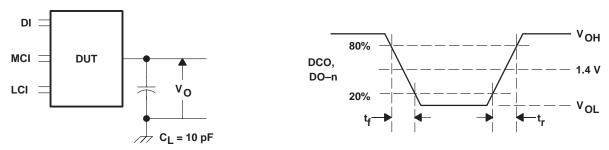


Figure 9. MCI to CO Timing Waveforms



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_{Γ} or $t_{\Gamma} \le 1$ ns, pulse repetition rate (PRR) = 100 Mpps, Pulse width = 5 ± 0.1 ns . C_{L} includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

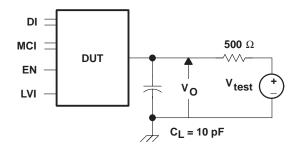
Figure 10. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_{Γ} or $t_{\Gamma} \le 1$ ns, MCI pulse repetition rate (PRR) = 50 Mpps, Pulse width = 10 ± 0.2 ns. LCI pulse repetition rate (PRR) = 5 Mpps, pulsewidth = 100 ± 2 ns. C_L includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

Figure 11. Timing Test Circuit and Waveforms





NOTE: VTEST = 2.5 V for tpzL or tpLz, VTEST = 0 V for tpzH or tpHz. All input pulses are supplied by a generator having the following characteristics: tr or tr ≤ 1 ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500±10 ns . CL includes instrumentation and fixture capacitance within 0,06 m of the D.U.T.

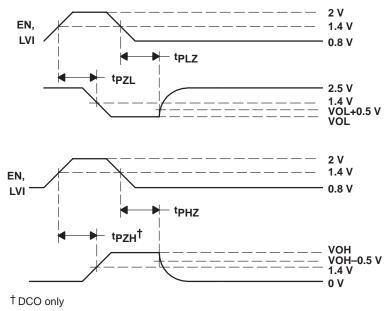


Figure 12. Enable/Disable Time Test Circuit and Waveforms

TYPICAL CHARACTERISTICS

AVERAGE SUPPLY CURRENT vs FREQUENCY

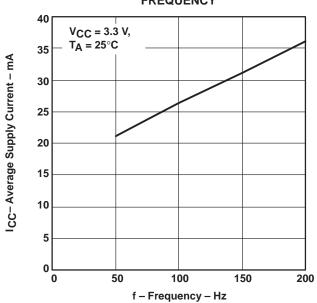


Figure 13. Average Supply Current vs Frequency

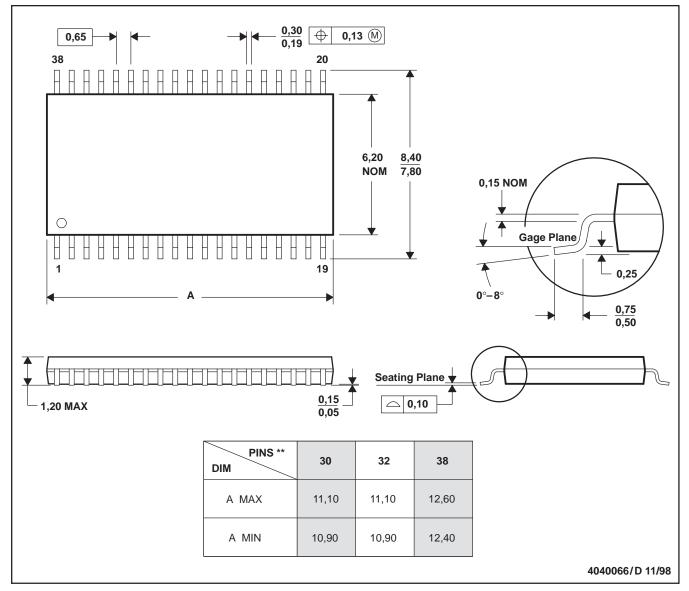


MECHANICAL DATA

DA (R-PDSO-G**)

38 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-153

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